

Turbo 2 ultrafast - high voltage rectifier

Main product characteristics

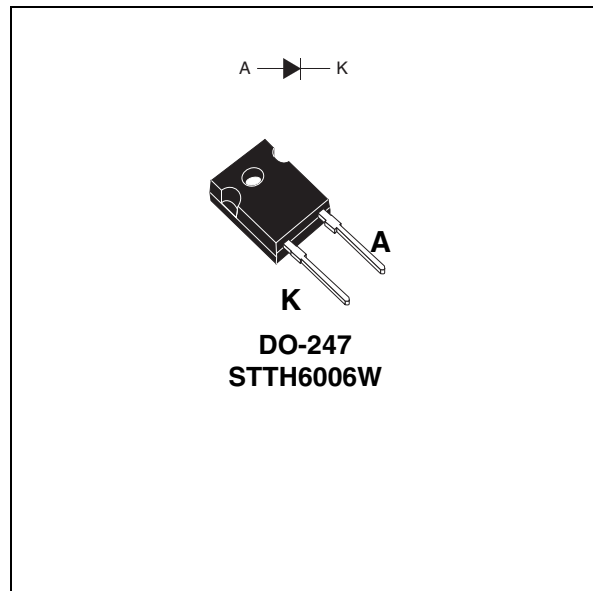
$I_{F(AV)}$	60 A
V_{RRM}	600 V
T_j	175° C
V_F (typ)	1.1 V
t_{rr} (max)	60 ns

Features and benefits

- Ultrafast switching
- Low reverse current
- Low thermal resistance
- Reduces conduction and switching losses

Description

The STTH6006W uses ST Turbo2 600V technology. This device is specially suited for use in switching power supplies, and industrial applications. The V_F / T_{rr} trade-off has been specially established to increase the performance in welding applications.



Order codes

Part Number	Marking
STTH6006W	STTH6006W

Table 1. Absolute ratings (limiting values per diode at 25° C, unless otherwise specified)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive peak reverse voltage	600	V
$I_{F(RMS)}$	RMS forward current	90	A
$I_{F(AV)}$	Average forward current, $\delta = 0.5$	$T_c = 95^\circ C$ 60	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10$ ms Sinusoidal 400	A
T_{stg}	Storage temperature range	-65 to + 175	°C
T_j	Maximum operating junction temperature ⁽¹⁾	175	°C

1. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ thermal runaway condition for a diode on its own heatsink

1 Characteristics

Table 2. Thermal parameters

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	0.75	°C/W

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ\text{C}$			50	μA
		$T_j = 125^\circ\text{C}$			160	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 60\text{ A}$		1.85	V
		$T_j = 150^\circ\text{C}$			1.10	

1. Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$

2. Pulse test: $t_p = 380\ \mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 1.07 \times I_{F(AV)} + 0.006 I_{F(RMS)}^2$$

Table 4. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ	Max.	Unit
t_{rr}	Reverse recovery time	$I_F = 0.5\text{ A}$, $I_{rr} = 0.25\text{ A}$, $I_R = 1\text{ A}$, $T_j = 25^\circ\text{C}$			60	ns
		$I_F = 1\text{ A}$, $dI_F/dt = -50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$, $T_j = 25^\circ\text{C}$		60	85	
I_{RM}	Reverse recovery current	$I_F = 60\text{ A}$, $dI_F/dt = -100\text{ A}/\mu\text{s}$, $V_R = 400\text{ V}$, $T_j = 150^\circ\text{C}$		10.5	14	
t_{fr}	Forward recovery time	$I_F = 60\text{ A}$ $dI_F/dt = 200\text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$, $T_j = 25^\circ\text{C}$			500	ns
V_{FP}	Forward recovery voltage	$I_F = 60\text{ A}$ $dI_F/dt = 200\text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$, $T_j = 25^\circ\text{C}$		3		V

Figure 1. Conduction losses versus average current

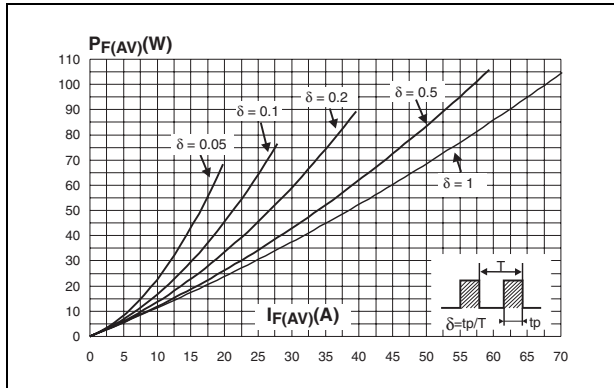


Figure 2. Forward voltage drop versus forward current

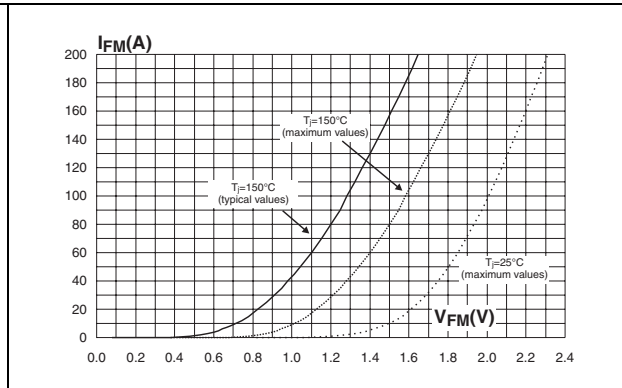


Figure 3. Relative variation of thermal impedance junction to case versus pulse duration

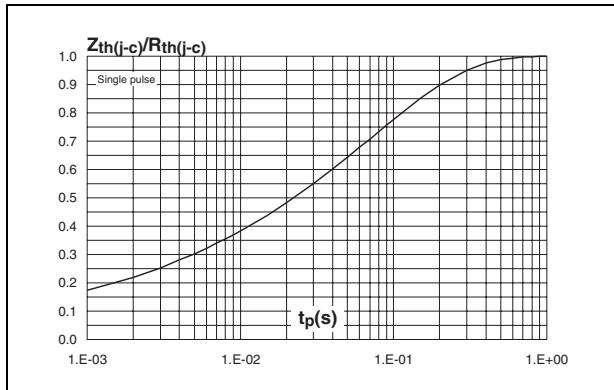


Figure 4. Peak reverse recovery current versus di_F/dt (typical values)

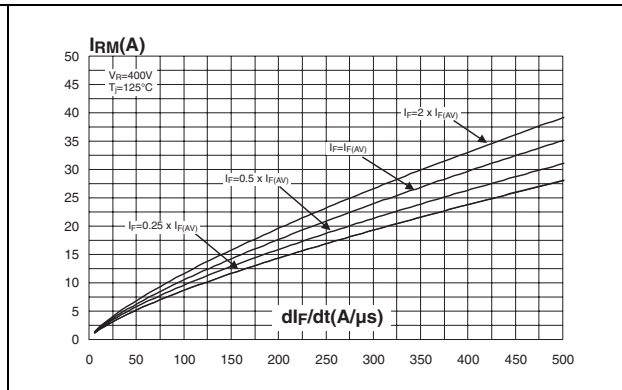


Figure 5. Reverse recovery time versus di_F/dt (typical values)

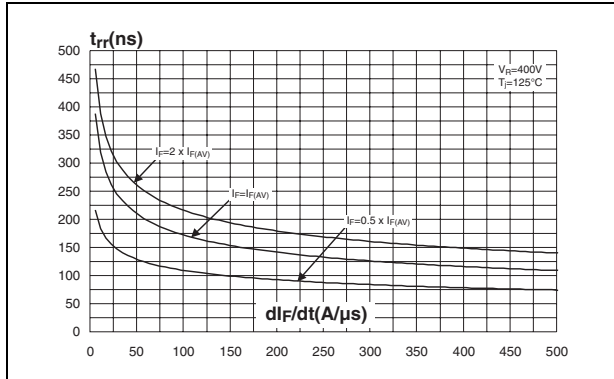


Figure 6. Reverse recovery charges versus di_F/dt (typical values)

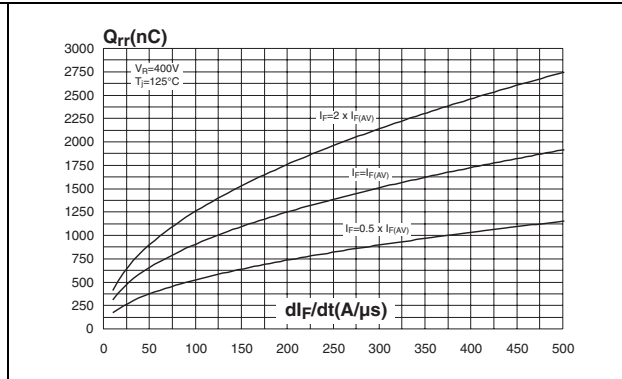


Figure 7. Softness factor versus di_F/dt (typical values)

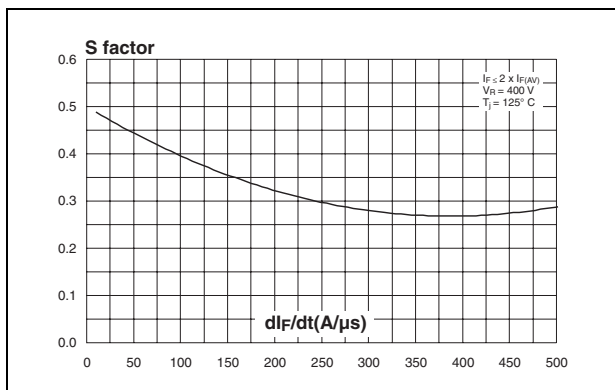


Figure 8. Relative variations of dynamic parameters versus junction temperature

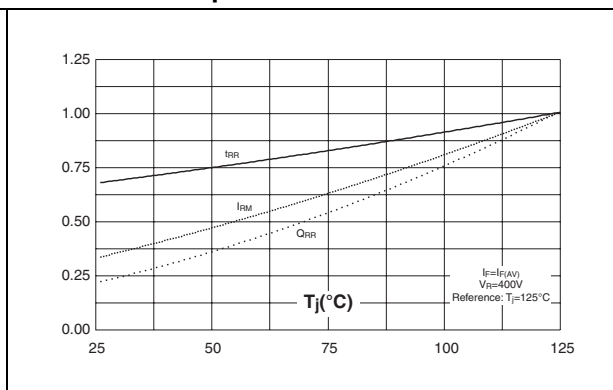


Figure 9. Transient peak forward voltage versus di_F/dt (typical values)

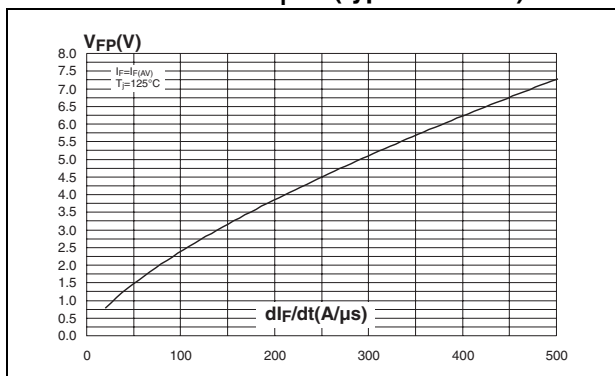


Figure 10. Forward recovery time versus di_F/dt (typical values)

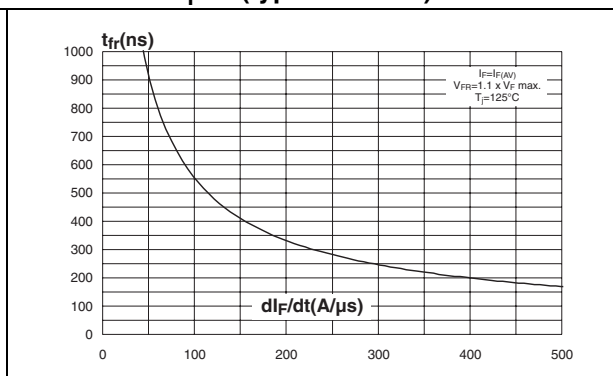
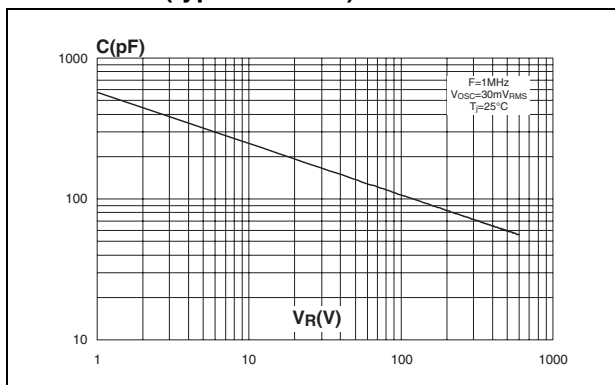


Figure 11. Junction capacitance versus reverse voltage applied (typical values)



2 Package mechanical data

Epoxy meets UL94, V0

Cooling method: by conduction (C)

Recommended torque value: 0.80 Nm

Maximum torque value: 1.0 Nm

Table 5. DO-247 dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

3 Ordering information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
STTH6006W	STTH6006W	DO-247	4.40 g	30	Tube

4 Revision history

Date	Revision	Description of Changes
18-May-2006	1	First issue.

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